



SOT2122-1

HVQFN124, thermal enhanced very thin quad flat package, no leads, 124 terminals, 0.4 mm pitch, 11.8 mm x 11 mm x 0.8 mm body

2 June 2020

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	HVQFN124
Package style descriptive code	HWQFN (thermal enhanced very very thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	04-01-2016
Manufacturer package code	MV-A300864-00

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	11.7	11.8	11.9	mm
package width	10.9	11	11.1	mm
package height	0.75	0.8	0.85	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	124	-	



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2 Package outline

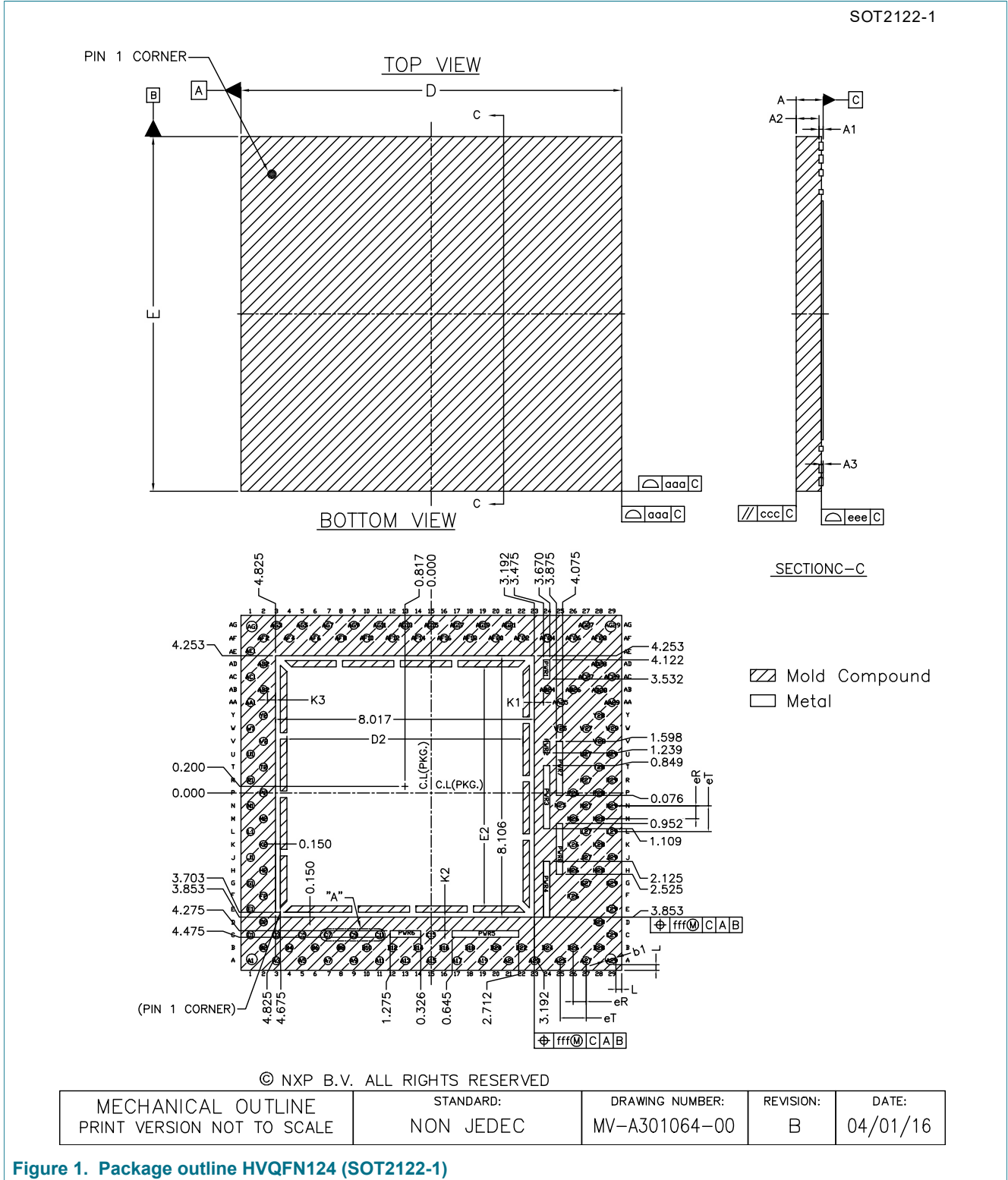
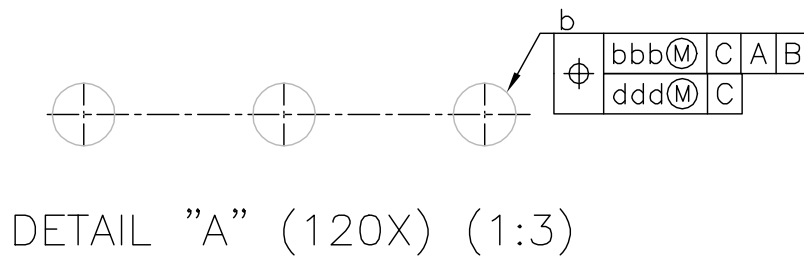


Figure 1. Package outline HVQFN124 (SOT2122-1)

HVQFN124, thermal enhanced very thin quad flat package, no leads, 124 terminals, 0.4 mm pitch, 11.8 mm x 11 mm x 0.8 mm body

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Figure 2. Package outline detail HVQFN124 (SOT2122-1)

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* CONTROLLING DIMENSION : MM

SYMBOL	MILLIMETER			INCH		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.750	0.800	0.850	0.030	0.031	0.033
A3	0.020	0.050	0.080	0.0008	0.002	0.003
A2	0.640	0.675	0.710	0.025	0.027	0.028
A1	0.120	0.130	0.140	0.005	0.005	0.006
b	0.200	0.250	0.300	0.008	0.010	0.012
b1	0.283	0.333	0.383	0.011	0.013	0.015
D	11.70	11.80	11.90	0.461	0.465	0.469
D2	7.217	7.317	7.417	0.284	0.288	0.292
E	10.90	11.00	11.10	0.429	0.433	0.437
E2	7.306	7.406	7.506	0.288	0.292	0.300
eT	0.800			0.032		
eR	0.400			0.016		
K1	0.233	0.283	0.333	0.009	0.011	0.013
K2	0.372	0.422	0.472	0.015	0.017	0.019
K3	0.200	0.250	0.300	0.008	0.010	0.012
L	0.125	0.175	0.225	0.005	0.007	0.009
TOLERANCES OF FORM AND POSITION						
aaa	0.150			0.006		
bbb	0.100			0.004		
ddd	0.050			0.002		
ccc	0.100			0.004		
eee	0.080			0.003		
fff	0.100			0.004		

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Figure 3. Package outline note HVQFN124 (SOT2122-1)

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3 Legal information

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